- High density cell design for ultra low Rdson
- Very low on-resistance $R_{DS(on)}$
- Good stability and uniformity with high E_{AS}
- 150 °C operating temperature
- Pb-free lead plating

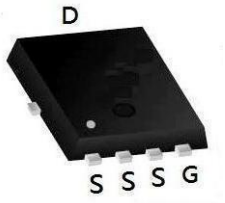
Product Summary

$V_{(BR)DSS}$	$R_{DS(ON)}$	I_D Max
30V	3.7mΩ @10V	60A
	6.0mΩ @ 4.5V	

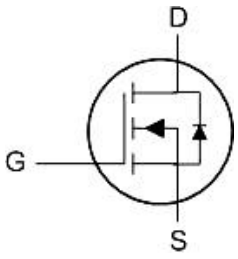
Description

The ZX 3080N is the high cell density Trench MOSFET, which provide excellent RDSON and gate charge for DC/DC converters application. The ZX 3080N meet the RoHS and GreenProduct requirement, 100% EAS guaranteed withfull function reliability approved.

PDFN3*3-8L



pin assignment



Schematic diagram

Package Marking and Ordering Information

Product	Package	Marking	Packing	Min Unit Quantity
ZX 3080N	PDFN3*3-8L	*	5000PCS/Reel	5000PCS

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current-Continuous	I_D	60	A
Drain Current-Continuous(T_C=100℃)	I_D (100℃)	30	A
Pulsed Drain Current	I_{DM}	150	A
Maximum Power Dissipation	P_D	45	W
Derating factor		0.36	W/℃
Single pulse avalanche energy (Note 5)	E_{AS}	150	mJ
Operating Junction and Storage Temperature Range	T_J,T_{STG}	-55 To 150	℃

Thermal Characteristic

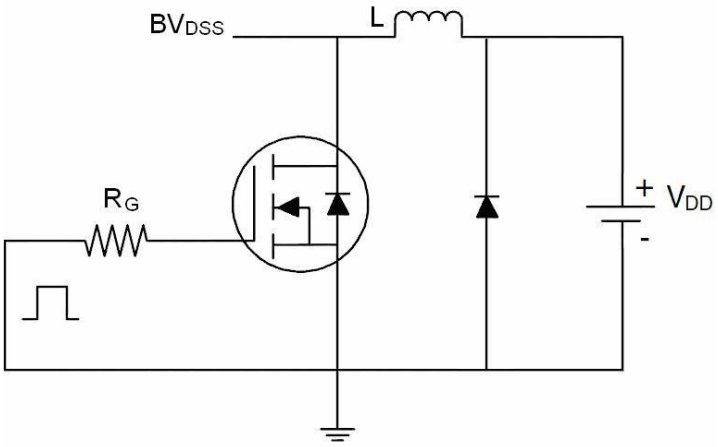
Thermal Resistance,Junction-to-Case(Note 2)	$R_{\theta JC}$	2.8	℃/W

Electrical Characteristics (TC=25℃unless otherwise noted)

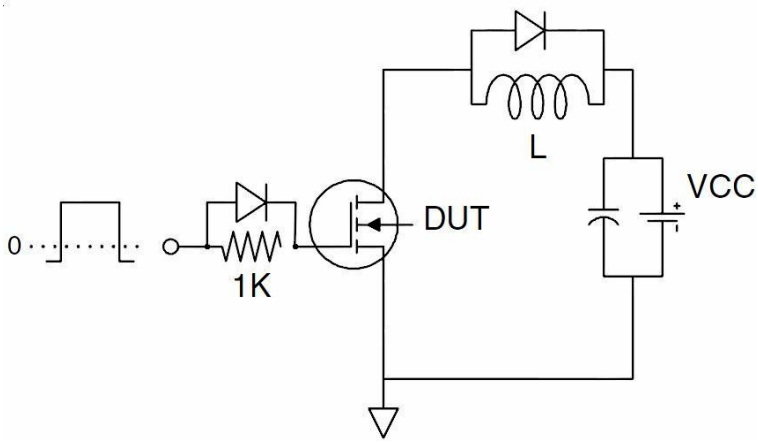
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA	30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=30V,V_{GS}=0V	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±20V,V_{DS}=0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=250μA	1	1.5	2.2	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=10V, I_D=30A	-	3.7	5.5	mΩ
		V_{GS}=4.5V, I_D=30A	-	6.0	8.0	
Forward Transconductance	g_{FS}	V_{DS}=5V,I_D=30A	30	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C_{lss}	V_{DS}=15V,V_{GS}=0V, F=1.0MHz	-	1784	-	PF
Output Capacitance	C_{oss}		-	266	-	PF
Reverse Transfer Capacitance	C_{rss}		-	212	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=5V,I_D=30A V_{GS}=10V,R_{GEN}=6Ω	-	7	-	nS
Turn-on Rise Time	t_r		-	6	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	30	-	nS
Turn-Off Fall Time	t_f		-	8	-	nS
Total Gate Charge	Q_g	V_{DS}=15V,I_D=30A , V_{GS}=10V	-	38.4	-	nC
Gate-Source Charge	Q_{gs}		-	5.8	-	nC
Gate-Drain Charge	Q_{gd}		-	7.9	-	nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	V_{GS}=0V,I_S=30A	-	0.85	1.2	V
Diode Forward Current (Note 2)	I_S		-	-	65	A
Reverse Recovery Time	t_{rr}	TJ = 25°C, I_F = 30A di/dt = 100A/μs(Note3)	-	-	47	nS
Reverse Recovery Charge	Qrr		-	-	25	nC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Test Circuit

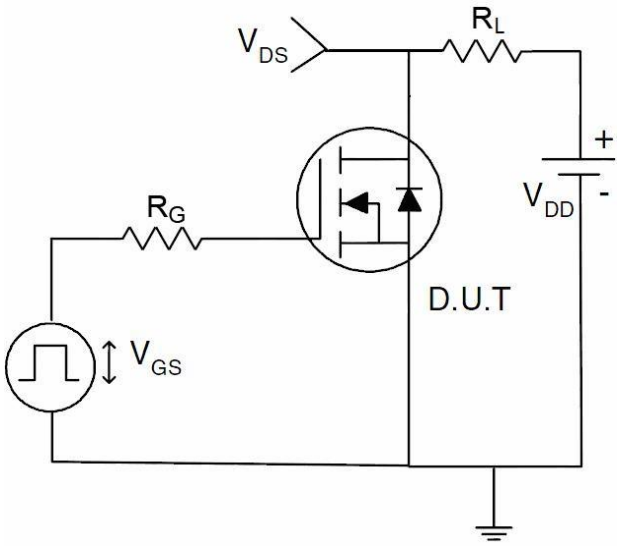
1) E_{AS} Test Circuits



2) Gate Charge Test Circuit



3) Switch Time Test Circuit



Typical Electrical and Thermal Characteristics (Curves)

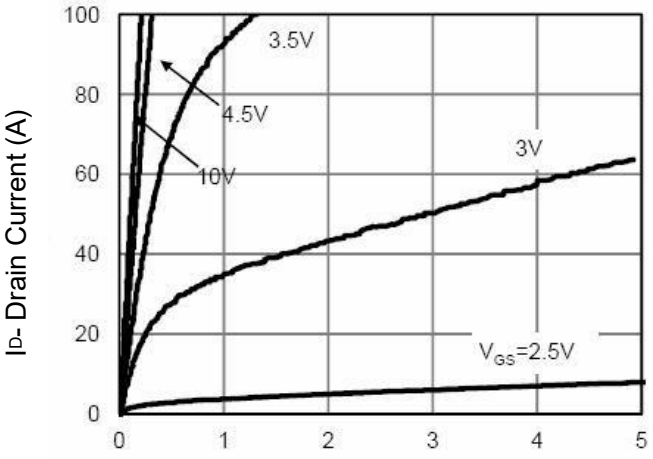


Figure 1 Output Characteristics

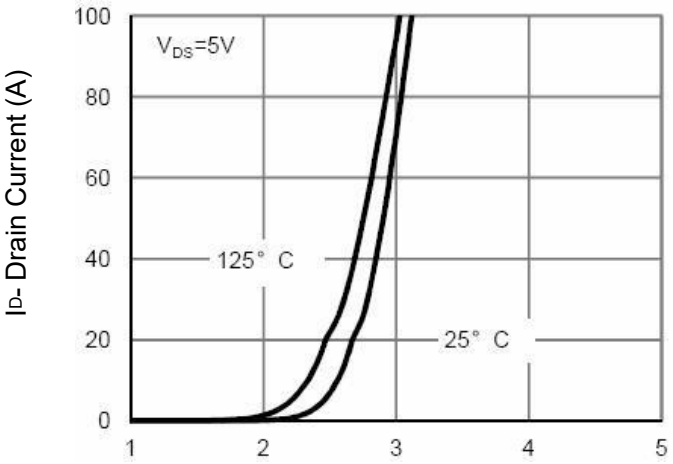


Figure 2 Transfer Characteristics

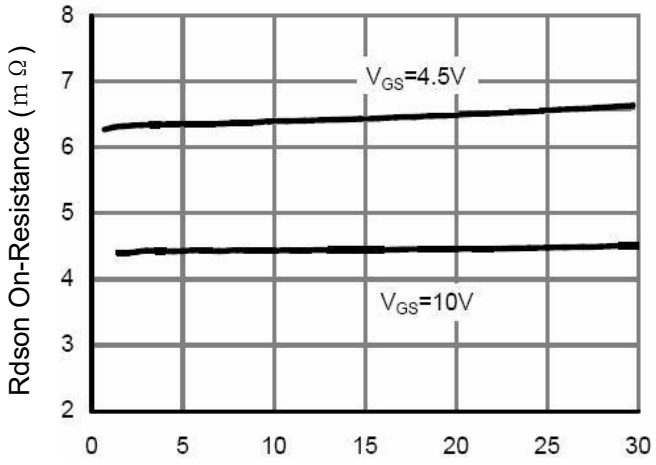


Figure 3 Rdson- Drain Current

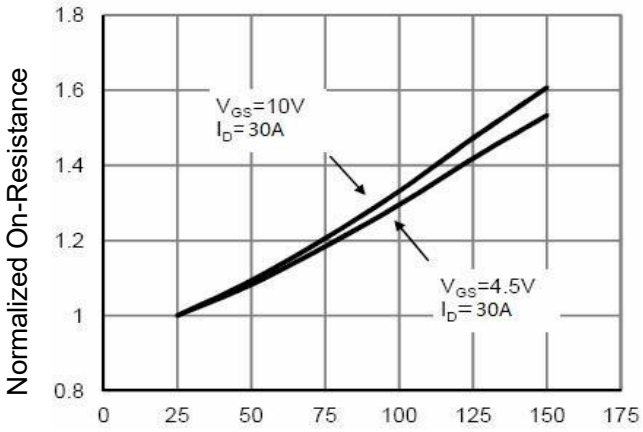


Figure 4 Rdson-Junction Temperature

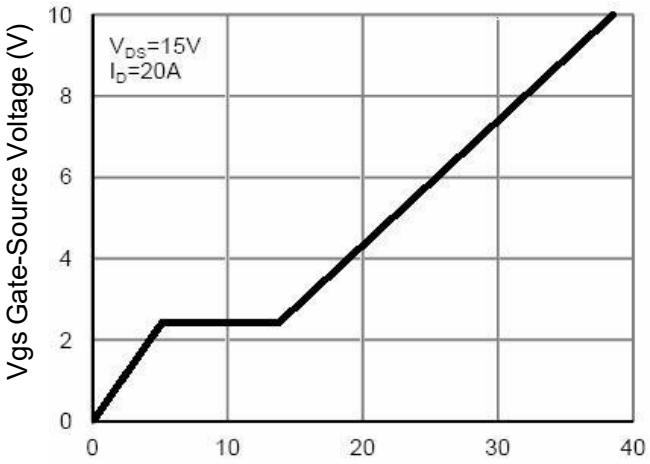


Figure 5 Gate Charge

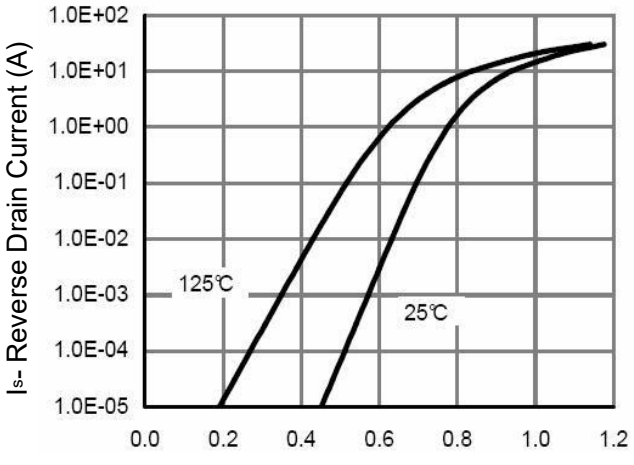


Figure 6 Source- Drain Diode Forward

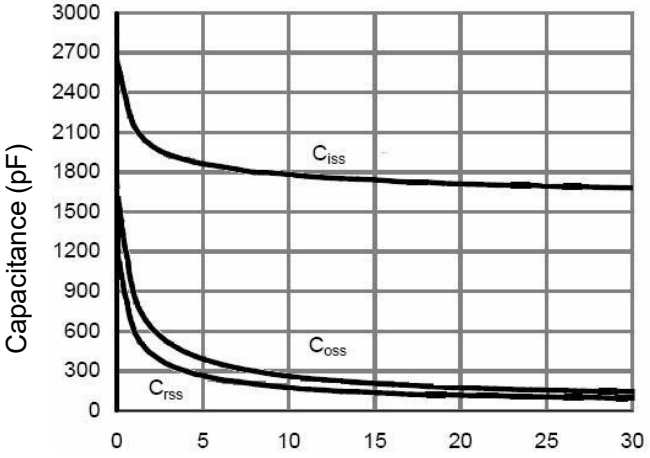


Figure 7 Capacitance vs Vds

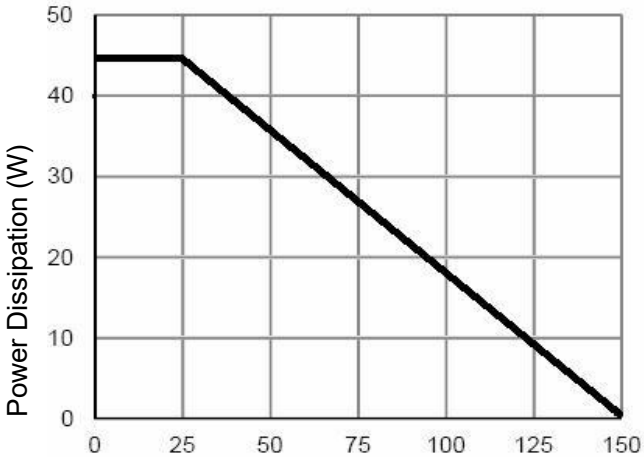


Figure 9 Power De-rating

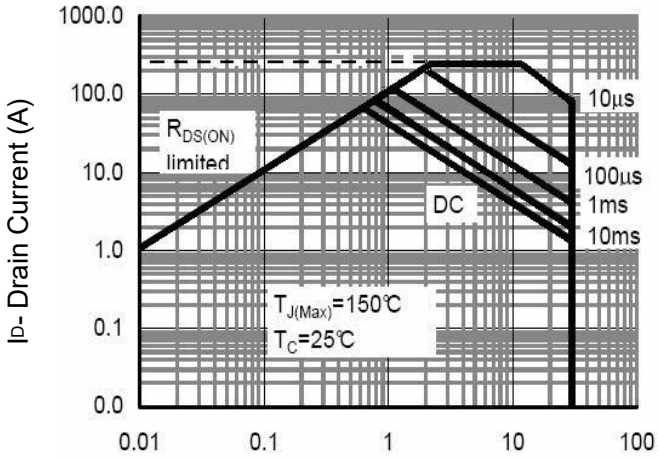


Figure 8 Safe Operation Area

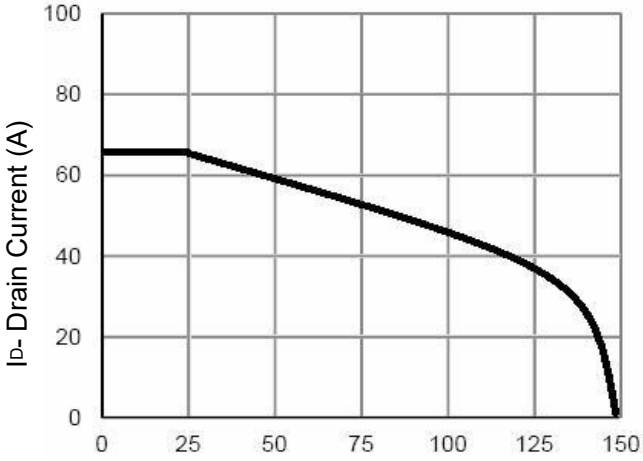


Figure 10 Current De-rating

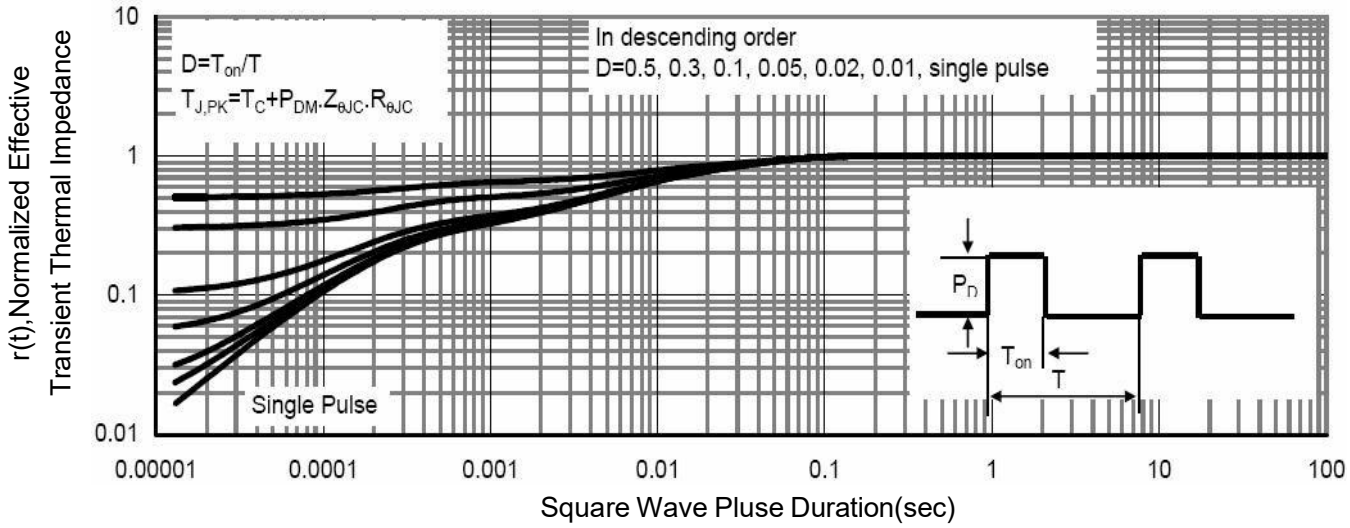
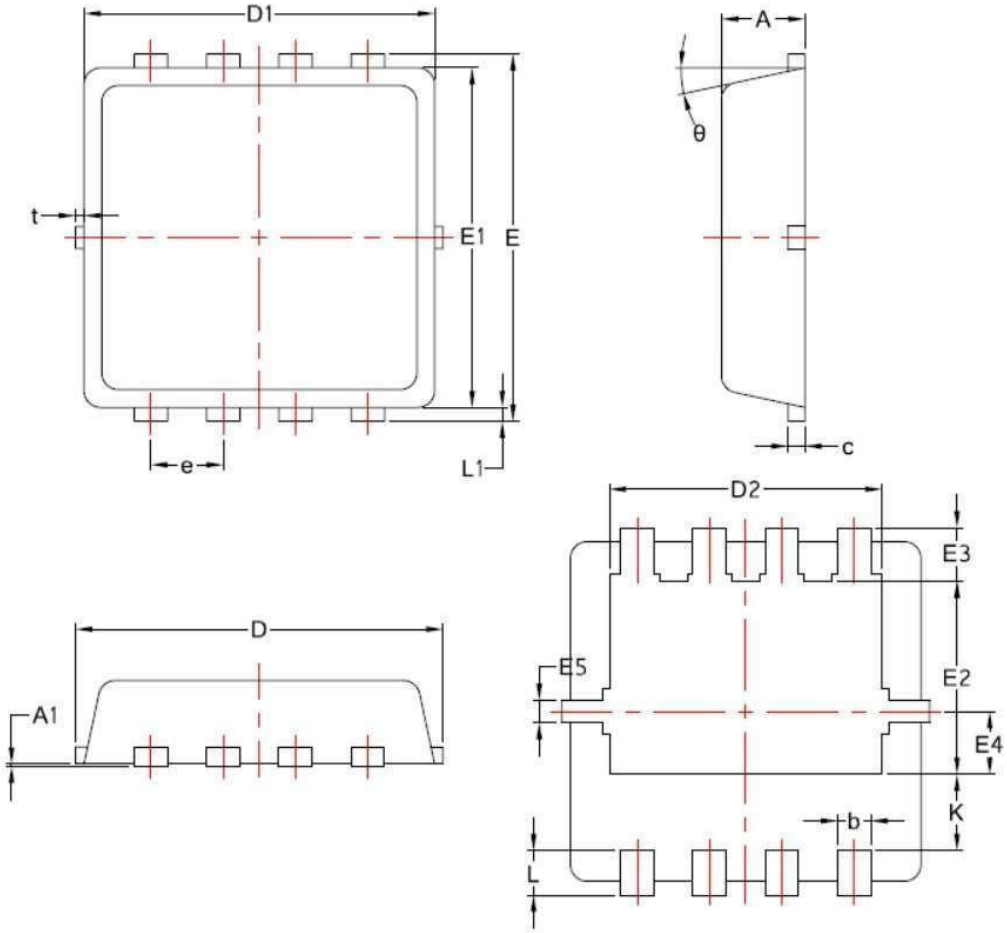


Figure 11 Normalized Maximum Transient Thermal Impedance

Package Mechanical Data-DFN3*3-8L-Single



SYMBOL	COMMON		
	MM		
	MIN	NOM	MAX
A	0.70	0.75	0.85
A1	/	/	0.05
b	0.20	0.30	0.40
c	0.10	0.152	0.25
D	3.15	3.30	3.45
D1	3.00	3.15	3.25
D2	2.29	2.45	2.65
E	3.15	3.30	3.45
E1	2.90	3.05	3.20
E2	1.54	1.74	1.94
E3	0.28	0.48	0.65
E4	0.37	0.57	0.77
E5	0.10	0.20	0.30
e	0.60	0.65	0.70
K	0.59	0.69	0.89
L	0.30	0.40	0.50
L1	0.06	0.125	0.20
t	0	0.075	0.13
θ	10°	12°	14°